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(54) DRIVING CIRCUIT

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(57)**ABSTRACT**

A driving circuit includes a detection circuit, a control circuit, and a power device. The detection circuit is coupled between first and second power terminals. The detection circuit generates a detection voltage at a detection node based on a first voltage of the first power terminal and a second voltage of the second power terminal. The control circuit includes a transistor device with a back-to-back connection structure that is coupled between a bonding pad and a first node and controlled by the detection voltage to generate a driving voltage at the first node for controlling the power device. In response to an electrostatic discharge event occurring on the bonding pad, the transistor device is turned on according to the detection voltage, and the power device is triggered by the driving voltage to provide a discharge path between the bonding pad and the second power termi-

